MLCC Tin/Lead Termination "B" (LD Series)

COG (NP0) – General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION) **Not RoHS Compliant**



*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.









0.1

10





Variation of Impedance with Ceramic Formulation Impedance vs. Frequency 1000 pF - C0G (NP0) vs X7R 0805





The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.

1000

100

Frequency, MHz

MLCC Tin/Lead Termination "B" COG (NP0) – Specifications and Test Methods



Paramet	er/Test	NP0 Specification Limits	Measuring	Conditions
Operating Temp	perature Range	-55°C to +125°C	Temperature C	ycle Chamber
Capac	itance	Within specified tolerance	Freq.: 1.0 MHz ± 10	% for cap ≤ 1000 pF
Q	!	<30 pF: Q≥ 400+20 x Cap Value ≥30 pF: Q≥ 1000	1.0 kHz ± 10% fc Voltage: 1.0	or cap > 1000 pF Wrms ± .2V
Insulation F	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 60 ± 5 secs @ roo	
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device wit for 500V	and discharge current 0 mA (max) h 150% of rated voltage
	Appearance	No defects	Deflectio	
Resistance to Flexure	Capacitance Variation	$\pm 5\%$ or $\pm .5$ pF, whichever is greater	Test Time: :	30 seconds 7 1mm/sec
Stresses	Q	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3	90	
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.	
	Appearance	No defects, <25% leaching of either end terminal		
	Capacitance Variation	≤ ±2.5% or ±.25 pF, whichever is greater		
Resistance to Solder Heat	Q	Meets Initial Values (As Above)	Dip device in eutectic seconds. Store at room	temperature for 24 ± 2
conter riedt	Insulation Resistance	Meets Initial Values (As Above)	hours before measurin	g electrical properties.
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	≤ ±2.5% or ±.25 pF, whichever is greater	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Q	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 hours at roo	
	Appearance	No visual defects	_	
	Capacitance Variation	$\leq \pm 3.0\%$ or $\pm .3$ pF, whichever is greater	Charge device with twi	
Load Life	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	chamber set a for 1000 hou Remove from test chamb	ırs (+48, -0).
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	temperature before me	for 24 hours
	Dielectric Strength	Meets Initial Values (As Above)		-
	Appearance	No visual defects		
	Capacitance Variation	$\leq \pm 5.0\%$ or $\pm .5$ pF, whichever is greater	Store in a test chamber s	set at 85°C + 2°C/ 85%
Load Humidity	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	5% relative humid (+48, -0) with rate	ity for 1000 hours d voltage applied.
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature for 24 ± 2 h	
	Dielectric Strength	Meets Initial Values (As Above)		



MLCC Tin/Lead Termination "B" COG (NP0) – Capacitance Range



PREFERRED SIZES ARE SHADED

SIZE Solderi Packag (L) Length W) Width (t) Terminal Cap (pF)	ng	1 (0.0	LD02 eflow/Wa All Paper .00 ± 0.1 040 ± 0.0	r		Reflow	03 //Wave			Do	LD05 flow/Way	/e				LD0 Reflow/			
Packag (L) Length W) Width (t) Terminal	ing mm (in.) mm (in.) mm (in.)	1 (0.0	All Paper .00 ± 0.1	r			/Wave			D_	flow//W/o	/e				Reflow/	Nave		
(L) Length W) Width (t) Terminal	mm (in.) mm (in.) mm (in.)	1 (0.0 0	.00 ± 0.1																_
W) Width (t) Terminal	(in.) mm (in.) mm (in.)	<u>(0.0</u> 0			1		aper				er/Embos		_		Pa	aper/Em			
(t) Terminal Cap	mm (in.) mm (in.)	0					± 0.15 ± 0.006)				.01 ± 0.20)79 ± 0.00				(3.20 ± 0 0.126 ± 0			
(t) Terminal Cap	(in.) mm (in.)	(0.0	.50 ± 0.1				± 0.000) ± 0.15				.25 ± 0.20				(1.60 ± 0			
Сар	(in.)		020 ± 0.0			(0.032 :	± 0.006)			(0.0	49 ± 0.00	08)			(0.063 ± 0			
Сар			.25 ± 0.1				± 0.15				.50 ± 0.2					0.50 ± 0			
	WVDC		010 ± 0.0		10	(0.014 :		100	10		$20 \pm 0.0^{\circ}$		~~~~	10		0.020 ± 0		000	
	0.5	16 C	25 C	50 C	16 G	25 G	50 G	100 G	16 J	25 J	50 J	100 J	200 J	16 J	25 J	50 J	100 J	200 J	500 J
(F*)	1.0	c	c	c	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.2	C	c	c	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.5	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	1.8	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	2.2 2.7	C C	C C	C C	G G	G G	G G	G G	J	J	J	J	J	J J	J	J	J	J	J
	3.3	C	C C	C	G	G	G	G	J	J	J	J	J J	J	J	J	J	J	J
	3.9	č	c	c	G	G	G	Ğ	J	J	Ĵ	Ĵ	Ĵ	J	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ
	4.7	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	5.6	С	С	C	G	G	G	G	٦ -	J	J	J	J	J	J	J	J	J	J
	6.8	C	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	8.2 10	C C	C C	C C	G	G G	G G	G G	J J	J	J J	J	J J	J J	J	J	J J	J	J
	12	c	c	c	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	15	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	18	С	C	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	22 27	C C	C C	C C	GG	G G	G G	G G	J	J	J	J	J J	J J	J	J	J	J	J
	33	C	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	39	č	c	c	G	G	G	G	J	Ĵ	J	Ĵ	J	J	J	Ĵ	J	Ĵ	Ĵ
	47	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	56	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	68 82	C C	C C	C C	G G	G G	G G	G G	J J	J J	J J	J	J J	J J	J	J J	J J	J	J
	100	<u>с</u>	C C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	120	č	c	c	G	G	Ğ	Ğ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	Ĵ
	150	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	180	С	С	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J
	220 270	C C	C C	C C	GG	G G	G G	G G	J J	J J	J	J	J M	J J	J	J	J J	J	M
	330	C	C C	C	G	G	G	G	J	J	J	J	M	J	J	J	J	J	M
	390	Č	c	c	G	G	G	G	J	J	J	J	М	J	Ĵ	J	J	J	M
	470	С	С	С	G	G	G		J	J	J	J	М	J	J	J	J	J	м
	560				G	G	G		J	J	J	J	М	J	J	J	J	J	M
	680 820				G	G G	G G		J	J J	J	J		J	J	J	J J	J	Р
	1000				G	G	G		J	J	J	J		J	J	J	J	Q	<u> </u>
	1200					G			J	J	J			J	J	J	J	Q	
	1500								J	J	J			J	J	J	М	Q	L
	1800								J	J	J			J	J	M	M		
	2200 2700								J	J	N N			J J	J	M M	P P		
	3300								J	J				J	J	M	P		
	3900								J	J				J	J	м	Р		
	4700								J	J				J	J	М	Р		L
	5600													J	J	м			
	6800 8200													M M	M				
Сар	0.010													M	M				
(pF)	0.012																		
	0.015		Ļ	. >		W-W-													└──
	0.018 0.022		-			223	\leq												
	0.022		(-		IJ	Ĵт												
	0.027		t (L											
	0.039			-															1
	0.047		Ļ		t														└──
	0.068			I	I	I 1													
	0.082 0.1																		
	WVDC	16	25	50	16	25	50	100	16	25	50	100	200	16	25	50	100	200	500
	SIZE		LD02				03				LD05					LDO			

Letter	А	С	E	G	J	K	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
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MLCC Tin/Lead Termination "B" COG (NP0) – Capacitance Range



PREFERRED SIZES ARE SHADED

SIZE	Ĩ			LD10					LD12				LD13			LD14	
Soldering	3		F	Reflow On	ly				Reflow Or	nly			Reflow Only			Reflow Only	
Packagin	-			er/Embos 3.20 + 0.2					II Embos: 4.50 ± 0.3				All Embossed 4.50 ± 0.30			All Embossed	
(L) Length	mm (in.)		(0.	126 ± 0.0	08)			(0	.177 ± 0.0	012)			(0.177 ± 0.012))		5.72 ± 0.25 (0.225 ± 0.010)
W) Width	mm (in.)			2.50 ± 0.2 098 ± 0.0					3.20 ± 0.2 .126 ± 0.0				6.40 ± 0.40 (0.252 ± 0.016))		6.35 ± 0.25 (0.250 ± 0.010)
(t) Terminal	mm (in.)			0.50 ± 0.2 020 ± 0.0					0.61 ± 0.3				0.61 ± 0.36 (0.024 ± 0.014))		0.64 ± 0.39 (0.025 ± 0.015)
	WVDC	25	50	100	200	500	25	50	100	200	500	50	100	200	50	100	200
Cap (pF)	0.5 1.0 1.2																
	1.5 1.8																
	2.2 2.7																W
	3.3 3.9																L IT
	4.7															$\neg \downarrow$	
	5.6 6.8 8.2															₹ ₽	
	10 12 15					L L											
	13 18 22					J J											
	27					J											
	39					J											
	47 56					J											
	68 82					J J											
	100 120					J											
	150 180 220					J J J											
	270 330					J											
	390 470					М											
	560	J	J	J	J	M											
	680 820	J	J	J	J	M M											
	1000 1200	J	J J	J	J M	M M	К К	K K	к К	K K	M	M M	M M	M M	M M	M	P P
	1500 1800	J	J	J	M M	М	K K	к к	К К	К К	M	M M	M	M	M	M	P P
	2200	J	J	J	Q		К	к	к	К	Р	М	м	М	М	м	Р
	2700 3300		J	J	Q		K P	K P	K P	P P	Q Q	M M	M M	M	M	M M	P P
	3900 4700	J	J J	M M			P P	P P	P P	P P	Q Y	M M	M M	M M	M M	M M	P P
	5600 6800	J	J J				P P	P P	P Q	P Q	Y Y	M M	M M	M M	M	M M	P P
Сар	8200 0.010	J J	J				P P	P P	Q	Q Q	Y Y	M M	M		M	M	P P
(pF)	0.012	J	J				Р	Р	Q	X	Y	м	М		М	М	Р
	0.015						P P	P P	Q X	X X	Y Y	M P	M M		M	M	Y Y
	0.022 0.027						P Q	P X	X X	X Z		P P			M P	Y Y	Y Y
	0.033						Q	Х	Х	Z		Р			Р	-	
	0.039 0.047						X X	X X	Z Z	Z Z		P P			P P		
	0.068 0.082						ZZ	Z Z	ZZ						P Q		
	0.1 WVDC	25	50	100	200	500	Z 25	Z 50	Z 100	200	500	50	100	200	Q 50	100	200
SIZE				LD10					LD12				LD13			LD14	

Letter	А	С	E	G	J	К	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
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X8R – General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.





X8R – Specifications and Test Methods

Paramet	ter/Test	X8R Specification Limits	Measuring	Conditions
Operating Tem	perature Range	-55°C to +150°C	Temperature C	ycle Chamber
Capac	itance	Within specified tolerance	Freg.: 1.0 k	(Hz + 10%
Dissipatio	on Factor	\leq 2.5% for \geq 50V DC rating \leq 3.5% for 25V DC and 16V DC rating	Voltage: 1.0	
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roc	
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current) mA (max) h 150% of rated voltage
	Appearance	No defects	Deflectio	n: 2mm
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3	90 r	mm
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.1	
	Appearance	No defects, <25% leaching of either end terminal		
	Capacitance Variation	≤ ±7.5%		
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro	
	Appearance	No visual defects		
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 test chamber set	
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h	
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects		
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi	
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated	d voltage applied.
inamany	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature an 24 ± 2 hours bef	d humidity for
	Dielectric Strength	Meets Initial Values (As Above)		ore measuring.





X8R – Capacitance Range

	SIZE	LD	03	LD	05	LD	06
	WVDC	25V	50V	25V	50V	25V	50V
271	Cap 270	G	G				
331	(pF) 330	G	G	J	J		
471	470	G	G	J	J		
681	680	G	G	J	J		
102	1000	G	G	J	J	J	J
152	1500	G	G	J	J	J	J
182	1800	G	G	J	J	J	J
222	2200	G	G	J	J	J	J
272	2700	G	G	J	J	J	J
332	3300	G	G	J	J	J	J
392	3900	G	G	J	J	J	J
472	4700	G	G	J	J	J	J
562	5600	G	G	J	J	J	J
682	6800	G	G	J	J	J	J
822	Cap 8200	G	G	J	J	J	J
103	(μF) 0.01	G	G	J	J	J	J
123	0.012	G	G	J	J	J	J
153	0.015	G	G	J	J	J	J
183	0.018	G	G	J	J	J	J
223	0.022	G	G	J	J	J	J
273	0.027	G	G	J	J	J	J
333	0.033	G	G	J	J	J	J
393	0.039	G	G	J	J	J	J
473	0.047	G	G	J	J	J	J
563	0.056	G		N	N	М	М
683	0.068	G		N	N	М	М
823	0.082			N	N	М	М
104	0.1			N	N	М	М
124	0.12			N	N	М	М
154	0.15			N	N	М	М
184	0.18			N		М	М
224	0.22			N		М	M
274	0.27					M	М
334	0.33					М	М
394	0.39					М	
474	0.47					М	
684	0.68						
824	0.82						
105	1						
	WVDC	25V	50V	25V	50V	25V	50V
	SIZE	LD	03	LD	05	LD	06

Letter	А	С	E	G	J	K	М	Ν	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
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X7R – General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/ Lead Termination "B" products.

Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.









Variation of Impedance with Chip Size Impedance vs. Frequency 10,000 pF X7R





20 40 60 80 100 Temperature C

120

Variation of Impedance with Chip Size Impedance vs. Frequency 100,000 pF - X7R







X7R – Specifications and Test Methods

Parame	ter/Test	X7R Specification Limits	Measuring	Conditions
Operating Tem	perature Range	-55°C to +125°C	Temperature C	ycle Chamber
Сарас	itance	Within specified tolerance	-	
Dissipati	on Factor	≤ 10% for ≥ 50V DC rating ≤ 12.5% for 25V DC rating ≤ 12.5% for 25V and 16V DC rating ≤ 12.5% for ≤ 10V DC rating	Freq.: 1.0 k Voltage: 1.0	
Insulation	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roc	
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current) mA (max) h 150% of rated voltage
	Appearance	No defects	Deflectio	
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3	90 r	mm
Solder	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.1	
	Appearance	No defects, <25% leaching of either end terminal	-	
	Capacitance Variation	≤ ±7.5%		
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.
	Dielectric Strength	Meets Initial Values (As Above)		1
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro	
	Appearance	No visual defects	-	
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 r test chamber set	
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou	
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h	
	Dielectric Strength	Meets Initial Values (As Above)		
	Appearance	No visual defects	1	
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi	
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated	d voltage applied.
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature an 24 ± 2 hours bef	d humidity for
	Dielectric Strength	Meets Initial Values (As Above)		ore measuring.





X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

								-																		
SIZE			LD02					LD03							LD05							LD				
Solderin			low/V					low/W							low/W	<u>/ave</u> ossed						Reflow				
Packagi	ng mm		ll Pap 00 ± 0					ll Pap 60 ± 0							<u>r/Emb</u> 01 ± 0						Pa	aper/Er 3.20 ±		ea		
(L) Length	(in.)		40 ± 0				(0.0	63 ± 0	.006)						79 ± 0						(0.126 ±	£ 0.00	8)		
W) Width	mm (in.)		50 ± 0 20 ± 0			-		81 ± 0 32 ± 0							25 ± 0 49 ± 0						(1.60 ± 0.063 ±		8)		
	mm		25 ± 0					35 ± 0							$\frac{49 \pm 0}{50 \pm 0}$							0.50 ±		5)		
(t) Terminal	(in.)		10 ± 0					14 ± 0							20 ± 0						(0.020 ±		0)		
WVDC		16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
Сар	100																									
(pF)	150																									
(P)	220			С																						
	330			C					G	G	G		J	J	J	J	J	J								К
	470			c					G	G	G		J	J	J	J	J	J								K
	680			c					G	G	G		J	J	J	J	J	J								K
	1000			C	-				G	G	G		J	J	J	J	J	J								K
	1500			c					G	G	0		J	J	J	J	J	J		J	J	J	J	J	J	M
	2200			c					G	G				J	J	J	J	J		J	J	J	J	J	J	M
	3300		С	C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
	4700		c	C C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M
	6800	С	c						G	G			J	J	J	J	J	J		J	J	J	J	J	J	P
Сар	0.010	<u>с</u>	C						G	G			J	J	J	J	J	J		J	J	J	J	J	J	P
μF)	0.010	c	U					G	G	0			J	J	J	J	J	J		J	J	J	J	J	M	Г
(µr)	0.013	C						G	G				J	J	J	J	J	N		J	J	J	J	J	M	
	0.022	<u>с</u>						G	G				J	J	J	J	N	IN		J	J	J	J	J	M	
	0.033	U					G	G	G				J	J	J	J	N			J	J	J	J	J	M	
	0.047						G	G	G				J				N			J	J				P	
	0.008		C*			G	G	G	G				J	J	J J	J	N			J	J	J	J	J P	P	
	0.10		U^		0	-	G	G	G				-	J		J							J			
	0.15				G G	G G							J	J	J	N	N N			J	J	J	J	Q		
	0.22				G	G							J	J	N N	N	N			J	J	J	J P	Q		
	0.33							J*												-				Q		
	0.47							J					N N	N	N	N	N			M M	M M	M	P	Q		
	1.0					J*	J*						N	N N	N N*					M	M	Q	Q O	Q Q		
	1.0					J	J						IN	IN	IN					P	Q	Q	L A	ų		
	2.2				J*										P*							Q				
	3.3				J^										P*					Q	Q	Q				
	3.3 4.7												P*	P*						0*	0*	0*				
	4.7											P*	P^	P"						Q^ 0*	0*	Q^				
	22				-							P"	P						Q*	ų.	Ų"	Q				
	47																		Q.							
	100																									
	WVDC	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500
	SIZE	10	LD02		0.5	10	10	LD03		100	200	0.5	10	10	LD05	50	100	200	0.3	10	10	<u> 25</u> LD		100	200	1 300
	JIZE		2002	-	ļ	-		2003						-	2003			-					00			

Letter	А	С	E	G	J	К	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	OSSED			

= Under Development



X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

SIZE					LD10					LD	12		LD	13		LD	20		LD	014
Soldering				Re	eflow On	у				Reflow	v Only		Reflow	v Only		Reflow	w Only		Reflow	w Only
Packagin	g				r/Embos					All Emb				bossed		All Em				bossed
(L) Length	mm				20 + 0.2					4.50 ±				± 0.30		5.70 ±				± 0.25
	(in.)				26 ± 0.0					(0.177 ±				± 0.012)		(0.224 :				± 0.010)
W) Width	mm				50 ± 0.2					3.20 ±				± 0.40		5.00 ±				± 0.25
,	(in.)				98 ± 0.0	/				(0.126 ±			· ·	± 0.016)			± 0.016)			± 0.010)
(t) Terminal	mm (in.)				50 ± 0.2 20 ± 0.0					0.61 ± (0.024 ±				± 0.36 ± 0.014)		0.64	± 0.39 ± 0.015)			± 0.39 ± 0.015)
WVDC	(m.)	10	16	25	20 ± 0.0 50	10)	200	500	50	100	200	500	50	100	25	<u>(0.0251</u> 50	100	200	50	100
Cap	100	10	10	25	50	100	200	500	- 50	100	200	500	50	100	20	- 50	100	200	50	100
(pF)	150																			
(pi)	220																			
[330																-1	\sim		
	470																$\langle -$)) Îī	-
	680															Ľ				-
	1000																			
	1500	J	J	J	J	J	J	М									·	∎t		
	2200	J	J	J	J	J	J	М									I		I	
	3300	J	J	J	J	J	J	М												
	4700	J	J	J	J	J	J	М												
	6800	J	J	J	J	J	J	M	K		I/	K				V	V	V		Р
	0.010	J J	J	J	J	J J	J	P	K K	K K	K K	K P	M	M M		X X	X X	X X	M M	P
	0.015	J	J	J	J	J	J	Q	K	K	ĸ	P	M	M		x	x	x	M	P
	0.022	J		J	J	J	J	0	K	K	K	F X	M	M		X	X	X	M	P
	0.047	J	J	J	J	J	J	Ŷ	ĸ	ĸ	ĸ	Z	M	M		x	x	x	M	P
	0.068	Ĵ	J	J	J	J	M		ĸ	ĸ	ĸ	Z	M	M		X	x	x	M	P
	0.10	J	J	J	J	J	М		K	K	К	Z	M	М		Х	X	Х	М	Р
	0.15	J	J	J	J	М	Z		К	к	Р		М	М		X	X	X	М	Р
	0.22	J	J	J	J	Р	Z		K	K	Р		М	М		X	X	X	М	Р
	0.33	J	J	J	J	Q			К	М	Х		М	М		Х	X	Х	М	Р
	0.47	М	М	М	М	Q			К	Р			M	М		X	X	X	M	Р
 	0.68	M	M	P	X	X			M	Q			M	P		X	X		M	P
	1.0	N	N	P	X	Z			M	X			M	Р		X	X		M	P
	1.5 2.2	N X	N X	Z Z	Z Z	Z Z			Z Z	ZZ			M			X X	X X		M M	X
¦	3.3	X	X	Z	Z	2			Z	2						X	Z		IVI	
ľ	3.3 4.7	x	X	Z	Z				Z	z						x	Z			
ľ	10	Ž	Z	Z	Z				2	-						z	Z			
i	22	Z	Z	-	-								1		Z	-				
ľ	47	_	-												_					
ľ	100																			
	WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100
SIZE					LD10					LD	12		LD	13		LD	20		LD	014

Letter	А	С	E	G	ſ	К	М	N	Р	Q	Х	Y	Z			
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79			
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)			
			PAPER			EMBOSSED										





X5R – General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

TYPICAL ELECTRICAL CHARACTERISTICS









X5R – Specifications and Test Methods

Parame	ter/Test	X5R Specification Limits	Measuring Conditions							
Operating Tem	perature Range	-55°C to +85°C	Temperature Cycle Chamber							
Сарас	itance	Within specified tolerance								
Dissipatio	on Factor	≤ 2.5% for ≥ 50V DC rating ≤ 3.0% for 25V, 35V DC rating ≤ 12.5% Max. for 16V DC rating and lower Contact Factory for DF by PN	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz							
Insulation I	Resistance	10,000MΩ or 500MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roo							
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50	and discharge current						
	Appearance	No defects	Deflectio	n: 2mm						
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3							
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)								
	Insulation Resistance	≥ Initial Value x 0.3	90 mm							
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.5							
	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance Variation	≤ ±7.5%								
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	seconds. Store at room	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.						
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties						
	Dielectric Strength	Meets Initial Values (As Above)		1						
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes						
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes						
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes						
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes						
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ± 2 hours at room temperature							
	Appearance	No visual defects								
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5X rated voltage in test chamber set at 85°C ± 2°C for 1000 hours (+48, -0). Note: Contact factory for *optional specification part numbers that are tested at < 1.5X rated voltage.							
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)								
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb							
	Dielectric Strength	Meets Initial Values (As Above)	temperature for 24 ± 2 h	ours defore measurin						
	Appearance	No visual defects								
	Capacitance Variation	≤ ±12.5%	 Store in a test chamber set at 85°C ± 2°C/ 85% 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring. 							
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)								
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)								
	Dielectric Strength	Meets Initial Values (As Above)								





X5R – Capacitance Range

PREFERRED SIZES ARE SHADED

								••••••••••••••••••••••••••••••••••••••																													
SIZE					LD02					LD03					LD05					LD06					LD10							LD	12				
Solderi	ing		R	eflo	w/Wa	ave				Reflo	w/W	Vave	9			Re	flow	/Wav	/e			Re	flow	/Wav	/e		Reflow/Wave										
Packag	ing			All I	Pape	er				All	Pa	ber			P	ape	r/En	nbo	sse	d	Р	ape	r/En	nbo	sse	d		Pa	per/	/Emb	osse	ed	_				
L) Length	mm			1.00	± 0.	10				1.60) ± C).15						0.20					.20 ±							0 ± 0							
	(in.)				± 0.0				((0.063			6)					0.00					26 ±					((0.12	6 ± 0	.008)		<u> </u>			
N) Width	mm (in.)				± 0. ± 0.				((0.81			5)					0.20					.60 ±)63 ±				2.50 ± 0.20 (0.098 ± 0.008)										
(4) T a must be a l	mm				± 0.				((0.3			5)					0.25					.50 ±							$\frac{0 \pm 0}{0 \pm 0}$							-
(t) Terminal	(in.)		(0.	010	± 0.0	006)			((0.014	4 ± C	0.00	6)			(0.0)20 ±	0.01	10)			(0.0)20 ±	0.01	10)			((0.02	0 ± 0	.010)					
WVDC	-	4	6.3	10	16	25	50	4	6.3	10	16	25	35	50	6.3	10	16	25	35	50	6.3	10	16	25	35	50	4	6.3	10	16	25	35	50	6.3	10	25	50
Cap	100																																				
(pF)	150						-																														
	220						C																									\vdash	<u> </u>	-	$\left \right $		-
	330						C																					1			>			- 		I	1
	470						C																					7	_	-1_	/	\sim	_	$\overline{}$	<u>`</u> ؟	\leq	
	680 1000			-	-	-	C C			-	-	-	<u> </u>					-	\vdash										<u>`</u> (\sim	\geq	7)]⊤	
							c																						C	-	.)		/			-	
	1500 2200						C																								~-	1					
	3300						C														_										1	t					
	4700					С								G																	1						
	6800					c								G																							
Сар	0.010				-	C								G							_											\vdash			\vdash		-
(µF)	0.015					c						G	G	G																							
(F)	0.022				С	c						G	G	G						Ν																	
	0.033				C	-						G	G	G						N													-				-
	0.047				С	С						G	G	G						Ν																	
	0.068				С							G		G						Ν																	
	0.10			С	С	С						G		G				Ν		Ν															\square		
	0.15											G						Ν	Ν																		
	0.22		C*	1							G	G						Ν	Ν							Q											
	0.33										G	G						Ν																	\square		
	0.47	C*	C*								G							Ν						Q	Q								Х	1			
	0.68										G							Ν																			
	1.0	C*	C*	C*					G	G	G	J*					Ν	Ν		P*				Q	Q						Х	Х	X				
	1.5																																				
	2.2	C*						G*	G*	J*	J*					Ν	Ν	Ν					Q	Q							Ζ	Х			\square		
	3.3							J*	J*	J*	J*				N	Ν					х	Х															
	4.7							J*	J*	J*					N	Ν	N*	N*			х	Х	Х	Х						Q	Z						
	10		L	<u> </u>	⊢	<u> </u>	<u> </u>	K*		<u> </u>					P	Ρ	Ρ	L		Ц	Х	Х	Х	Х				-	X	Z	Z		⊢	⊢	\square	Z	-
	22 47														P*						X X	Х	Х	х				Z Z*	Ζ	Ζ	Z	4					
	47 100																				~						Z*	Z^ Z									l
	WVDC	4	6.3	10	16	25	50	4	6.3	10	16	25	35	50	6.3	10	16	25	35	50	6.3	10	16	25	35	50		6.3	10	16	25	35	50	6.3	10	25	5
	WVDC 4 6.3 10 16 25 50 4 SIZE LD02			4 6.3 10 16 25 35 50 LD03				6.3 10 16 25 35 50 LD05			LD06					LD10				_	0 6.3 10 25 50																

Letter	A	С	E	G	J	K	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSFD			

*Optional Specifications – Contact factory

NOTE: Contact factory for non-specified capacitance values

